

Chunqing Wang

List of Publications by Year in descending order

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327
papers

4,005
citations

126708

33
h-index

197535

49
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331
all docs

331
docs citations

331
times ranked

2577
citing authors

#	ARTICLE	IF	CITATIONS
1	Growth behavior of Cu/Al intermetallic compounds and cracks in copper ball bonds during isothermal aging. <i>Microelectronics Reliability</i> , 2008, 48, 416-424.	0.9	211
2	Rapid pressureless low-temperature sintering of Ag nanoparticles for high-power density electronic packaging. <i>Scripta Materialia</i> , 2013, 69, 789-792.	2.6	146
3	Ni@CeO ₂ composite cathode material for hydrogen evolution reaction in alkaline electrolyte. <i>International Journal of Hydrogen Energy</i> , 2012, 37, 13921-13932.	3.8	94
4	Formation mechanism and orientation of Cu ₃ Sn grains in Cu-Sn intermetallic compound joints. <i>Materials Letters</i> , 2013, 110, 137-140.	1.3	74
5	Fabrication of interconnects using pressureless low temperature sintered Ag nanoparticles. <i>Materials Letters</i> , 2012, 85, 61-63.	1.3	70
6	Multiferroic properties of La and Mn co-doped BiFeO ₃ nanofibers by sol-gel and electrospinning technique. <i>Materials Letters</i> , 2013, 90, 45-48.	1.3	70
7	Rapid formation of Cu/Cu ₃ Sn/Cu joints using ultrasonic bonding process at ambient temperature. <i>Applied Physics Letters</i> , 2013, 102, .	1.5	68
8	Influence of aging treatment on deformation behavior of 96.5Sn3.5Ag lead-free solder alloy during in situ tensile tests. <i>Journal of Alloys and Compounds</i> , 2007, 428, 274-285.	2.8	67
9	Relationship between morphologies and orientations of Cu ₆ Sn ₅ grains in Sn _{3.0} Ag _{0.5} Cu solder joints on different Cu pads. <i>Materials Characterization</i> , 2014, 88, 58-68.	1.9	63
10	Interfacial reactions of eutectic Sn _{3.5} Ag and pure tin solders with Cu substrates during liquid-state soldering. <i>Intermetallics</i> , 2012, 25, 86-94.	1.8	57
11	Sintering mechanism of the Cu-Ag core-shell nanoparticle paste at low temperature in ambient air. <i>RSC Advances</i> , 2016, 6, 91783-91790.	1.7	56
12	Recent Progress in Ohmic Contacts to Silicon Carbide for High-Temperature Applications. <i>Journal of Electronic Materials</i> , 2016, 45, 267-284.	1.0	56
13	Nanometer-Scale Heterogeneous Interfacial Sapphire Wafer Bonding for Enabling Plasmonic-Enhanced Nanofluidic Mid-Infrared Spectroscopy. <i>ACS Nano</i> , 2020, 14, 12159-12172.	7.3	54
14	Mechanisms for low-temperature direct bonding of Si/Si and quartz/quartz via VUV/O ₃ activation. <i>RSC Advances</i> , 2018, 8, 11528-11535.	1.7	52
15	Effects of bump size on deformation and fracture behavior of Sn _{3.0} Ag _{0.5} Cu/Cu solder joints during shear testing. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2011, 529, 468-478.	2.6	51
16	Ultrarapid formation of homogeneous Cu ₆ Sn ₅ and Cu ₃ Sn intermetallic compound joints at room temperature using ultrasonic waves. <i>Ultrasonics Sonochemistry</i> , 2014, 21, 924-929.	3.8	51
17	Microstructures, corrosion and mechanical properties of as-cast Mg-Zn-Y (Gd) alloys. <i>Transactions of Nonferrous Metals Society of China</i> , 2015, 25, 2172-2180.	1.7	51
18	Extremely fast formation of Cu Sn intermetallic compounds in Cu/Sn/Cu system via a micro-resistance spot welding process. <i>Journal of Alloys and Compounds</i> , 2016, 687, 667-673.	2.8	50

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19	Aging effects on fracture behavior of 63Sn37Pb eutectic solder during tensile tests under the SEM. , 2004, 384, 314-314.		50
20	Low Temperature Sintering Cu ₆ Sn ₅ Nanoparticles for Superplastic and Superuniform High Temperature Circuit Interconnections. Small, 2015, 11, 4097-4103.	5.2	48
21	Silk fibroin film-coated MgZnCa alloy with enhanced in vitro and in vivo performance prepared using surface activation. Acta Biomaterialia, 2019, 91, 99-111.	4.1	48
22	Investigation of ultrasonic copper wire wedge bonding on Au/Ni plated Cu substrates at ambient temperature. Journal of Materials Processing Technology, 2008, 208, 179-186.	3.1	47
23	Mechanical properties and fracture mechanisms of Sn-3.0Ag-0.5Cu solder alloys and joints at cryogenic temperatures. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2017, 684, 697-705.	2.6	42
24	Glass-on-LiNbO ₃ heterostructure formed via a two-step plasma activated low-temperature direct bonding method. Applied Surface Science, 2018, 459, 621-629.	3.1	42
25	Electrochemical synthesis of NiS/CeO ₂ composite electrodes for hydrogen evolution reaction. Journal of Power Sources, 2013, 230, 10-14.	4.0	41
26	Electronic structure mechanism for the wettability of Sn-based solder alloys. Journal of Electronic Materials, 2002, 31, 185-190.	1.0	40
27	Determination of the Elastic Properties of Cu ₃ Sn Through First-Principles Calculations. Journal of Electronic Materials, 2008, 37, 477-482.	1.0	38
28	Finite element modeling of electron beam welding of a large complex Al alloy structure by parallel computations. Journal of Materials Processing Technology, 2008, 199, 41-48.	3.1	38
29	Electrodeposition fabrication of Cu@Ni core shell nanowire network for highly stable transparent conductive films. Chemical Engineering Journal, 2020, 390, 124495.	6.6	38
30	Microstructural study of copper free air balls in thermosonic wire bonding. Microelectronic Engineering, 2008, 85, 1815-1819.	1.1	36
31	Intermetallic compounds formation at interface between PBGA solder ball and Au/Ni/Cu/BT PCB substrate after laser reflow processes. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2002, 95, 254-262.	1.7	35
32	Effect of electric current on grain orientation and mechanical properties of Cu-Sn intermetallic compounds joints. Journal of Alloys and Compounds, 2018, 753, 203-211.	2.8	35
33	Effect of electronic flame off parameters on copper bonding wire: Free-air ball deformability, heat affected zone length, heat affected zone breaking force. Microelectronic Engineering, 2009, 86, 2094-2103.	1.1	34
34	Ultrafast formation of unidirectional and reliable Cu ₃ Sn-based intermetallic joints assisted by electric current. Intermetallics, 2017, 80, 26-32.	1.8	34
35	Effect of Cu grain size on the voiding propensity at the interface of SnAgCu/Cu solder joints. Materials Letters, 2015, 144, 97-99.	1.3	33
36	Microstructure evolution and thermostability of bondline based on Cu@Sn core-shell structured microparticles under high-temperature conditions. Materials and Design, 2017, 131, 196-203.	3.3	33

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37	Recent Progress in Rapid Sintering of Nanosilver for Electronics Applications. <i>Micromachines</i> , 2018, 9, 346.	1.4	33
38	Direct bonding of silicon and quartz glass using VUV/O ₃ activation and a multistep low-temperature annealing process. <i>Applied Surface Science</i> , 2018, 453, 416-422.	3.1	33
39	Reliability and failure analysis of fine copper wire bonds encapsulated with commercial epoxy molding compound. <i>Microelectronics Reliability</i> , 2011, 51, 157-165.	0.9	30
40	The influence of strengthening and recrystallization to the cracking behavior of Ni, Sb, Bi alloyed SnAgCu solder during thermal cycling. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 652, 264-270.	2.6	30
41	Enhanced shear strength of Cu-Sn intermetallic interconnects with interlocking dendrites under fluxless electric current-assisted bonding process. <i>Journal of Materials Science</i> , 2017, 52, 1943-1954.	1.7	30
42	Room-temperature direct bonding of silicon and quartz glass wafers. <i>Applied Physics Letters</i> , 2017, 110, .	1.5	29
43	Chemical and thermal robust tri-layer rGO/Ag NWs/GO composite film for wearable heaters. <i>Composites Science and Technology</i> , 2019, 174, 76-83.	3.8	29
44	Low-temperature-solderable intermetallic nanoparticles for 3D printable flexible electronics. <i>Acta Materialia</i> , 2019, 162, 163-175.	3.8	29
45	Investigation on Sn grain number and crystal orientation in the Sn-Ag-Cu/Cu solder joints of different sizes. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 1174-1180.	1.1	28
46	Electromigration-induced intermetallic growth and voids formation in symmetrical Cu/Sn/Cu and Cu/Intermetallic compounds (IMCs)/Cu joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2015, 26, 2674-2681.	1.1	27
47	Cohesively enhanced electrical conductivity and thermal stability of silver nanowire networks by nickel ion bridge joining. <i>Scientific Reports</i> , 2018, 8, 5260.	1.6	27
48	High-efficiency extraction synthesis for high-purity copper nanowires and their applications in flexible transparent electrodes. <i>Nano Materials Science</i> , 2020, 2, 164-171.	3.9	27
49	Interdiffusion of Al-Ni system enhanced by ultrasonic vibration at ambient temperature. <i>Ultrasonics</i> , 2006, 45, 61-65.	2.1	26
50	Room-Temperature Direct Bonding Using Fluorine Containing Plasma Activation. <i>Journal of the Electrochemical Society</i> , 2011, 158, H525.	1.3	26
51	Morphologies and grain orientations of Cu-Sn intermetallic compounds in Sn _{3.0} Ag _{0.5} Cu/Cu solder joints. <i>Materials Letters</i> , 2012, 86, 157-160.	1.3	26
52	Fabrication of SiC/Si, SiC/SiO ₂ , and SiC/glass heterostructures via VUV/O ₃ activated direct bonding at low temperature. <i>Ceramics International</i> , 2019, 45, 4094-4098.	2.3	26
53	Bonding wire characterization using automatic deformability measurement. <i>Microelectronic Engineering</i> , 2008, 85, 1795-1803.	1.1	25
54	A Comparative Study: Void Formation in Silicon Wafer Direct Bonding by Oxygen Plasma Activation with and without Fluorine. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P7-P13.	0.9	25

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55	Growth kinetics of Cu ₆ Sn ₅ intermetallic compound in Cu-liquid Sn interfacial reaction enhanced by electric current. <i>Scientific Reports</i> , 2018, 8, 1775.	1.6	25
56	Evolution of the bond interface during ultrasonic Al-Si wire wedge bonding process. <i>Journal of Materials Processing Technology</i> , 2007, 182, 202-206.	3.1	24
57	Nano features of Al/Au ultrasonic bond interface observed by high resolution transmission electron microscopy. <i>Materials Characterization</i> , 2008, 59, 1419-1424.	1.9	24
58	Bonding mechanism of ultrasonic wedge bonding of copper wire on Au/Ni/Cu substrate. <i>Transactions of Nonferrous Metals Society of China</i> , 2008, 18, 132-137.	1.7	24
59	Progress in wafer bonding technology towards MEMS, high-power electronics, optoelectronics, and optofluidics. <i>International Journal of Optomechatronics</i> , 2020, 14, 94-118.	3.3	24
60	Investigation of fluorine containing plasma activation for room-temperature bonding of Si-based materials. <i>Microelectronics Reliability</i> , 2012, 52, 347-351.	0.9	23
61	Fabrication and characterization of silk fibroin coating on APTES pretreated Mg-Zn-Ca alloy. <i>Materials Science and Engineering C</i> , 2020, 110, 110742.	3.8	23
62	TEM observation of interfacial compounds of SnAgCu/ENIG solder bump after laser soldering and subsequent hot air reflows. <i>Materials Letters</i> , 2016, 163, 254-257.	1.3	22
63	A novel cobalt-free CO ₂ -stable perovskite-type oxygen permeable membrane. <i>Journal of Membrane Science</i> , 2019, 573, 504-510.	4.1	22
64	An integrated system for prediction and analysis of solder interconnection shapes. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2000, 23, 87-92.	1.6	21
65	Effects of ultrasonic irradiation and cooling rate on the solidification microstructure of Sn-3.0Ag-0.5Cu alloy. <i>Journal of Materials Processing Technology</i> , 2014, 214, 13-20.	3.1	21
66	Phase transformation and fracture behavior of Cu/In/Cu joints formed by solid-liquid interdiffusion bonding. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 4170-4178.	1.1	21
67	Ultrafine-Grain and Isotropic Cu/SAC305/Cu Solder Interconnects Fabricated by High-Intensity Ultrasound-Assisted Solidification. <i>Journal of Electronic Materials</i> , 2014, 43, 2467-2478.	1.0	21
68	Recycled low-temperature direct bonding of Si/glass and glass/glass chips for detachable micro/nanofluidic devices. <i>Journal of Materials Science and Technology</i> , 2020, 46, 156-167.	5.6	21
69	Low-Temperature Co-hydroxylated Cu/SiO ₂ Hybrid Bonding Strategy for a Memory-Centric Chip Architecture. <i>ACS Applied Materials & Interfaces</i> , 2021, 13, 38866-38876.	4.0	21
70	Effect of solidification on solder bump formation in solder jet process: Simulation and experiment. <i>Transactions of Nonferrous Metals Society of China</i> , 2008, 18, 1201-1208.	1.7	20
71	Effect of Au-Sn IMCs formation and morphologies on shear properties of laser reflowed micro-solder joints. <i>Soldering and Surface Mount Technology</i> , 2015, 27, 45-51.	0.9	20
72	A facile method for direct bonding of single-crystalline SiC to Si, SiO ₂ , and glass using VUV irradiation. <i>Applied Surface Science</i> , 2019, 471, 196-204.	3.1	20

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73	Aging effects on fracture behavior of 63Sn37Pb eutectic solder during tensile tests under the SEM. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2004, 384, 314-323.	2.6	19
74	In situ quantitative study of microstructural evolution at the interface of Sn3.0Ag0.5Cu/Cu solder joint during solid state aging. <i>Journal of Alloys and Compounds</i> , 2015, 634, 94-98.	2.8	19
75	Direct Homo/Heterogeneous Bonding of Silicon and Glass Using Vacuum Ultraviolet Irradiation in Air. <i>Journal of the Electrochemical Society</i> , 2018, 165, H3093-H3098.	1.3	19
76	Maximum shear stress-controlled uniaxial tensile deformation and fracture mechanisms and constitutive relations of Sn-Pb eutectic alloy at cryogenic temperatures. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2021, 819, 141523.	2.6	19
77	Effect of intermetallic compounds on fracture behaviors of Sn3.0Ag0.5Cu lead-free solder joints during in situ tensile test. <i>Journal of Materials Science: Materials in Electronics</i> , 2012, 23, 136-147.	1.1	18
78	Cu nanoparticles of low polydispersity synthesized by a double-template method and their stability. <i>Colloid and Polymer Science</i> , 2014, 292, 715-722.	1.0	18
79	Comparison of interface evolution of ultrasonic aluminum and gold wire wedge bonds during thermal aging. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2007, 447, 111-118.	2.6	17
80	Cross-Interaction of Interfacial Reactions in Ni (Au/Ni/Cu)-SnAg-Cu Solder Joints during Reflow Soldering and Thermal Aging. <i>Journal of Electronic Materials</i> , 2007, 36, 26-32.	1.0	17
81	Mechanical properties and microstructures of hybrid ultrasonic resistance brazing of WC-Co/BeCu. <i>Journal of Materials Processing Technology</i> , 2012, 212, 1885-1891.	3.1	17
82	Degradation behaviors of micro ball grid array (µBGA) solder joints under the coupled effects of electromigration and thermal stress. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 11583-11592.	1.1	17
83	Facile synthesis of Cu-Ag hybrid nanowires with strong surface-enhanced Raman scattering sensitivity. <i>CrystEngComm</i> , 2016, 18, 1200-1206.	1.3	17
84	One-Step Fabrication of 3D Nanohierarchical Nickel Nanomace Array To Sinter with Silver NPs and the Interfacial Analysis. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 4798-4807.	4.0	17
85	Mechanisms for Room-Temperature Fluorine Containing Plasma Activated Bonding. <i>ECS Journal of Solid State Science and Technology</i> , 2017, 6, P373-P378.	0.9	17
86	Thermomechanical behaviour of PBGA package during laser and hot air reflow soldering. <i>Modelling and Simulation in Materials Science and Engineering</i> , 2004, 12, 235-243.	0.8	16
87	The effects of pulsed Nd:YAG laser irradiation on surface energy of copper. <i>Applied Surface Science</i> , 2006, 252, 4257-4263.	3.1	16
88	Determination of the Elastic Properties of Au5Sn and AuSn from Ab Initio Calculations. <i>Journal of Electronic Materials</i> , 2008, 37, 968-974.	1.0	16
89	Study of electroless Sn-coated Cu microparticles and their application as a high temperature thermal interface material. <i>Surface and Coatings Technology</i> , 2017, 319, 230-240.	2.2	16
90	High-Efficient Vacuum Ultraviolet-Ozone Assist-Deposited Polydopamine for Poly(lactic-co-glycolic acid)-Coated Pure Zn toward Biodegradable Cardiovascular Stent Applications. <i>ACS Applied Materials & Interfaces</i> , 2022, 14, 3536-3550.	4.0	16

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91	Synthesis of Co-doped barium strontium titanate nanofibers by sol-gel/electrospinning process. <i>Materials Letters</i> , 2012, 75, 207-210.	1.3	15
92	The role of chloride ions in rapid synthesis of ultra-long silver nanowires for flexible electrodes. <i>Materials Research Express</i> , 2016, 3, 075007.	0.8	15
93	Superior rate and long-lived performance of few-layered black phosphorus-based hybrid anode for lithium-ion batteries. <i>Electrochimica Acta</i> , 2022, 403, 139697.	2.6	15
94	Study of copper free air ball in thermosonic copper ball bonding. , 0, , .		14
95	Fabrication of multiferroic Ba _{0.7} Sr _{0.3} TiO ₃ ∆Ni _{0.8} Zn _{0.2} Fe ₂ O ₄ composite nanofibers by electrospinning. <i>Materials Letters</i> , 2013, 91, 55-58.	1.3	14
96	Low-temperature wafer direct bonding of silicon and quartz glass by a two-step wet chemical surface cleaning. <i>Japanese Journal of Applied Physics</i> , 2018, 57, 02BD02.	0.8	14
97	Effect of Diamond Additions on Wettability and Distribution of SnAgCu Composite Solder. <i>Journal of Materials Science and Technology</i> , 2012, 28, 661-665.	5.6	13
98	Scanning electron microscope in-situ investigation of fracture behavior in 96.5Sn3.5Ag lead-free solder. <i>Journal of Electronic Materials</i> , 2005, 34, 1324-1335.	1.0	12
99	In situ TEM observation of microcrack nucleation and propagation in pure tin solder. <i>Materials Science and Engineering B: Solid-State Materials for Advanced Technology</i> , 2006, 127, 62-69.	1.7	12
100	Synthesis of multiferroic Bi _{0.9} La _{0.1} Fe _{0.95} Mn _{0.05} O ₃ ∆Ba _{0.7} Sr _{0.3} TiO ₃ ∆Ni _{0.8} Zn _{0.2} Fe ₂ O ₄ nanotubes with one closed end using a template-assisted sol-gel process. <i>CrystEngComm</i> , 2013, 15, 2147.	1.3	12
101	The Investigation of Quality of Life in 87 Chinese Patients with Disorders of Sex Development. <i>BioMed Research International</i> , 2015, 2015, 1-6.	0.9	12
102	The Fabrication of Micro-Array Channels with the Ultrafine-Grained LZ91 Mg-Li Alloy by Micro-Embossing. <i>Micromachines</i> , 2018, 9, 55.	1.4	12
103	Low-temperature direct bonding of Si and quartz glass using the APTES modification. <i>Ceramics International</i> , 2019, 45, 16670-16675.	2.3	12
104	Rapid pressureless and low-temperature bonding of large-area power chips by sintering two-step activated Ag paste. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 6497-6505.	1.1	12
105	Evolution of deformation near the triple point of grain junctions in Sn-based solders during in situ tensile test. <i>Materials Letters</i> , 2005, 59, 697-700.	1.3	11
106	Fabrication of Cu ₆ Sn ₅ single-crystal layer for under-bump metallization in flip-chip packaging. <i>Intermetallics</i> , 2013, 42, 52-55.	1.8	11
107	Effect of the Silver Content of SnAgCu Solder on the Interfacial Reaction and on the Reliability of Angle Joints Fabricated by Laser-Jet Soldering. <i>Journal of Electronic Materials</i> , 2015, 44, 733-743.	1.0	11
108	One-Step Fabrication of Copper Nanopillar Array-Filled AAO Films by Pulse Electrodeposition for Anisotropic Thermal Conductive Interconnectors. <i>ACS Omega</i> , 2019, 4, 6092-6096.	1.6	11

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109	Oxidation and Au-Sn reaction of laser reflowed micro-solder joints protected by N ₂ or exposed to air atmosphere. Soldering and Surface Mount Technology, 2012, 24, 191-196.	0.9	10
110	Optimization and modeling for one-step synthesis process of Ag-Cu nano-particles using DOE methodology. Journal of Materials Science: Materials in Electronics, 2016, 27, 4265-4274.	1.1	10
111	Micro heat pipe device utilizing extended nanofluidics. RSC Advances, 2017, 7, 50591-50597.	1.7	10
112	Solderless bonding with nanoporous copper as interlayer for high-temperature applications. Microelectronics Reliability, 2018, 80, 198-204.	0.9	10
113	Communication-Ag NW Networks Enhanced by Ni Electroplating for Flexible Transparent Electrodes. Journal of the Electrochemical Society, 2018, 165, D328-D330.	1.3	10
114	Shear Deformation Behaviors of Sn _{3.5} Ag Lead-free Solder Samples. Journal of Materials Science and Technology, 2013, 29, 471-479.	5.6	9
115	Joining of Silver Nanowires by Femtosecond Laser Irradiation Method. Materials Transactions, 2015, 56, 981-983.	0.4	9
116	Computer simulation of three-dimensional castellated solder joint geometry in surface mount technology. Modelling and Simulation in Materials Science and Engineering, 1998, 6, 557-565.	0.8	8
117	Evolution of Cu/Al Intermetallic Compounds in the Copper Bump bonds during Aging Process. , 2007, , .		8
118	Effects of Solder Volume on Formation and Redeposition of Au-Containing Intermetallics in Ni/Au-SnAgCu-Ni(P) Solder Joints. Journal of Electronic Materials, 2007, 36, 33-39.	1.0	8
119	Mechanism of low temperature Cu-In Solid-Liquid Interdiffusion bonding in 3D package. , 2012, , .		8
120	Parallel-gap resistance welding between gold-plated silver interconnects and silver electrodes in germanium solar cells. , 2014, , .		8
121	Fabrication of Al ₂ O ₃ -Mullite-AlN Multiphase Ceramic Layer on W-Cu Substrates for Power Semiconductor Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 182-187.	1.4	8
122	Microstructures and Properties of As-Cast Mg ₉₂ Zn ₄ Y ₄ and Mg ₉₂ Zn ₄ Y ₃ Gd ₁ Alloys with LPSO Phase. Rare Metal Materials and Engineering, 2015, 44, 1617-1622.	0.8	8
123	Effects of temperature and dispersants on the phases and morphology of Ag-Cu nanoparticles. Journal of Materials Science: Materials in Electronics, 2016, 27, 10065-10069.	1.1	8
124	Low temperature nanojoining of silver-copper nanopaste as die attach material for high temperature packaging. Journal of Materials Science: Materials in Electronics, 2017, 28, 5446-5451.	1.1	8
125	Room-Temperature Direct Heterogeneous Bonding of Glass and Polystyrene Substrates. Journal of the Electrochemical Society, 2018, 165, B3091-B3097.	1.3	8
126	Communication-Defect-Free Direct Bonding for High-Performance Glass-On-LiNbO ₃ Devices. Journal of the Electrochemical Society, 2018, 165, B727-B729.	1.3	8

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127	VUV/O ₃ activated direct heterogeneous bonding towards high-performance LiNbO ₃ -based optical devices. <i>Applied Surface Science</i> , 2019, 495, 143576.	3.1	8
128	Dissimilatory iron reduction and potential methane production in Chagan Lake wetland soils with carbon addition. <i>Wetlands Ecology and Management</i> , 2021, 29, 369-379.	0.7	8
129	Interaction kinetics between PBGA solder balls and Au/Ni/Cu metallisation during laser reflow bumping. <i>Soldering and Surface Mount Technology</i> , 2003, 15, 17-21.	0.9	8
130	In situ measurement of bond resistance varying with process parameters during ultrasonic wedge bonding. <i>Journal of Materials Processing Technology</i> , 2009, 209, 139-144.	3.1	7
131	The effects of humidity and temperature aging test on flexible packaging LED module. , 2013, , .		7
132	Laser Sintering of Nano-Ag Particle Paste for High-Temperature Electronics Assembly. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2017, 7, 1050-1057.	1.4	7
133	Nd:YAG laser surface treatment of copper to improve the wettability of Sn _{3.5} Ag solder on copper. <i>Surface and Coatings Technology</i> , 2005, 200, 2181-2186.	2.2	6
134	In-situ SEM observation on fracture behaviors of Sn-based solder alloys. <i>Journal of Materials Science</i> , 2005, 40, 1993-2001.	1.7	6
135	The effect of voids on thermal conductivity of solder joints. , 2012, , .		6
136	Formation of AuSn _x IMCs in Sn _{3.5} Ag _{0.75} Cu micro-solder joints fabricated by laser and hot air reflow processes. <i>Journal of Materials Science: Materials in Electronics</i> , 2013, 24, 217-223.	1.1	6
137	Preparation and Sintering Properties of Ag ₂₇ Cu ₂ Sn Nanopaste as Die Attach Material. <i>Journal of Electronic Materials</i> , 2016, 45, 5436-5442.	1.0	6
138	Communicationâ€™ Fluorinated Plasma Treatments Using PTFE Substrates for Room-Temperature Silicon Wafer Direct Bonding. <i>ECS Journal of Solid State Science and Technology</i> , 2016, 5, P393-P395.	0.9	6
139	MoirÃ©-Based Alignment Using Centrosymmetric Grating Marks for High-Precision Wafer Bonding. <i>Micromachines</i> , 2019, 10, 339.	1.4	6
140	Unique buoyancy-force-based kinetics determination of beta to alpha phase transformation in bulk tin plates. <i>Materials and Design</i> , 2020, 190, 108550.	3.3	6
141	Low-temperature Cu/SiO ₂ hybrid bonding using a novel two-step cooperative surface activation. , 2021, , .		6
142	Interfacial Characterization and Bonding Mechanism of Ultrasonic Wedge Bonding. , 2006, , .		5
143	Three-dimensional modelling of solder droplet impact onto a groove. <i>Journal Physics D: Applied Physics</i> , 2008, 41, 245503.	1.3	5
144	Self-assembly of three-dimensional microstructures in MEMS via fluxless laser reflow soldering. , 2011, , .		5

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145	Surface-Tension-Driven Self-Assembly of 3-D Microcomponents by Using Laser Reflow Soldering and Wire Limiting Mechanisms. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 168-176.	1.4	5
146	Effects of Ba _{0.7} Sr _{0.3} TiO ₃ -based buffer layers and La/Mn doping on the crystallization behavior and multiferroic properties of BiFeO ₃ thin films. RSC Advances, 2014, 4, 55889-55896.	1.7	5
147	Characterization of the Microstructure of an AlN-Mullite-Al ₂ O ₃ Ceramic Layer on WCu Composite Alloy for Microelectronic Application. Journal of Electronic Materials, 2015, 44, 4154-4160.	1.0	5
148	Low-temperature bonding process for the fabrication of hybrid glass membrane organ-on-a-chip devices. Journal of Micro/Nanolithography, MEMS, and MOEMS, 2016, 15, 044502.	1.0	5
149	Study on preparation and rapid laser sintering process of nano silver pastes. , 2017, , .		5
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